

Description

The SI4447DY-T1-E3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} =-40 V I_D = -13A

 $R_{DS(ON)}$ < 19m Ω @ V_{GS}=10V

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

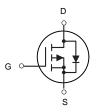
Product ID	Pack	Brand	Qty(PCS)
SI4447DY-T1-E3	SOP-8	HXY MOSFET	3000

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Symbol	Parameter	Rating	Units
Vds	Drain-Source Voltage	- 40	V
VGS	Gate-Source Voltage	±20	V
I _D @T _A =25℃	Drain Current ³ , V _{GS} @ 10V	-13	А
IDM	Pulsed Drain Current ¹	-52	А
P _D @T _A =25℃	Total Power Dissipation	3	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	41	°C/W



SOP-8



P-Channel MOSFET



SI4447DY-T1-E3

P-Channel Enhancement Mode MOSFET

Electrical Characteristics (TJ = 25°C, unless otherwise noted)

Parameter		Symbol Test Conditions		Min.	Тур.	Max.	Unit	
Static Characteristics		I	1		1			
Drain-Source Breakdown Voltage		V (BR)DSS V _{GS} = 0V, I _D = -250µA		-40	-	-	V	
Gate-body Leakage current		lgss	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain Current	TJ=25℃	ldss	V _{DS} = -40V, V _{GS} = 0V	-	-	-1	μA	
	T_=100°C			-	-	-100		
Gate-Threshold Voltage		V _{GS(th)}	V_{DS} = V_{GS} , I_D = -250 μ A	-1.0	-1.5	-2.2	V	
		_	V _{GS} = -10V, I _D = -10A	-	14.0			
Drain-Source On-Resistance ⁴		R _{DS(on)}	V_{GS} = -4.5V, I_D = -5 A	-	19.5	25	mΩ	
Forward Transconductance ⁴		g fs	V _{DS} = -10V, I _D = -10A	-	44	-	S	
Dynamic Characteristics ⁵								
Input Capacitance		Ciss	V _{DS} = -20V, V _{GS} =0V, f =1MHz	-	2525	-	pF	
Output Capacitance		Coss		-	190	-		
Reverse Transfer Capacitance		Crss		-	172	-		
Gate Resistance		Rg	f =1MHz	-	10	-	Ω	
Switching Characteristics	5 ⁵	•					1	
Total Gate Charge	Total Gate Charge			-	35	-	nC	
Gate-Source Charge		Qgs	V _{GS} = -10V,V _{DS} = -20V, I _D = -10A	-	5.5	-		
Gate-Drain Charge		Q _{gd}		-	8	-		
Turn-On Delay Time		t _{d(on)}		-	14.5	-	ns	
Rise Time		tr	V _{GS} = -10V, V _{DD} = -20V,	-	20.2	-		
Turn-Off Delay Time		t _{d(off)}	$R_{G} = 3\Omega, I_{D} = -10A$	-	32	-		
Fall Time		tr	-	-	10	-		
Drain-Source Body Diode	Character	istics	1	1	1	1	1	
Diode Forward Voltage ⁴		V _{SD}	I _S = -10A, V _{GS} = 0V	-	-	-1.2	V	
Continuous Source Current	Tc=25°C	ls	-	-	_	-13	А	

Note :

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C.

2. The EAS data shows Max. rating . The test condition is V_{DD}= -25V, V_{GS}= -10V, L= 0.1mH, I_{AS}= -34A.

- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.

5. This value is guaranteed by design hence it is not included in the production test.



SI4447DY-T1-E3 P-Channel Enhancement Mode MOSFET

Typical Characteristics

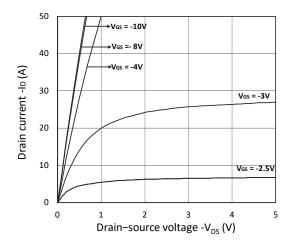


Figure 1. Output Characteristics

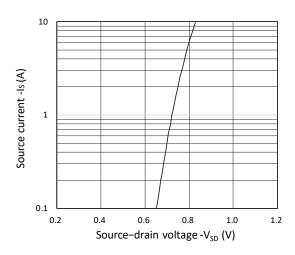


Figure 3. Forward Characteristics of Reverse

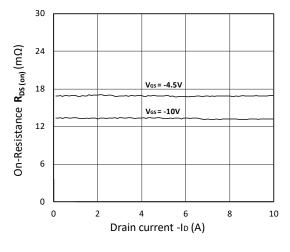


Figure 5. $R_{DS(ON)}$ vs. I_D

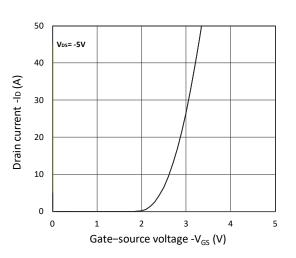


Figure 2. Transfer Characteristics

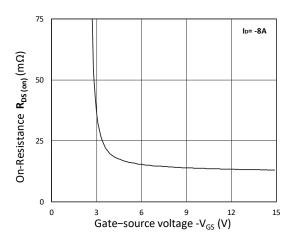


Figure 4. R_{DS(ON)} vs. V_{GS}

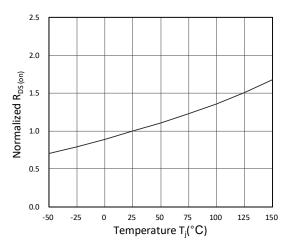


Figure 6. Normalized $R_{\text{DS(on)}}\,vs.$ Temperature



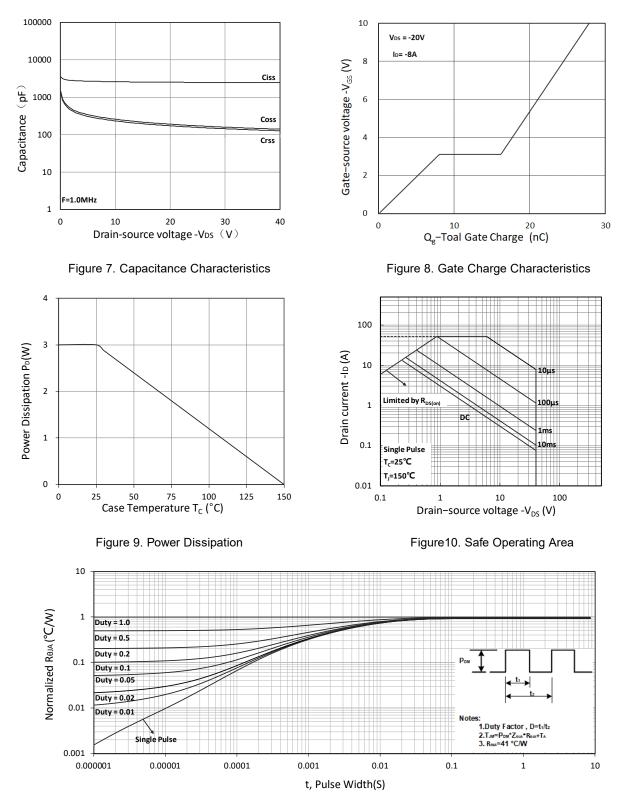
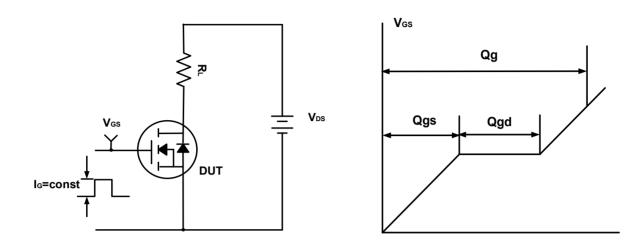


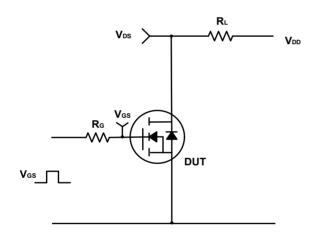
Figure 11. Normalized Maximum Transient Thermal Impedance



Test Circuit









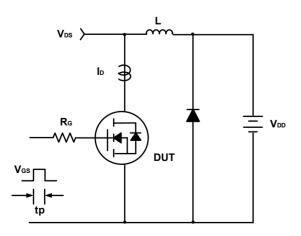
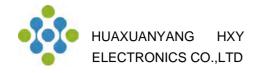
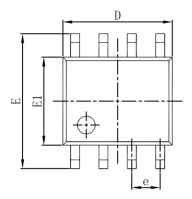


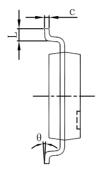
Figure C. Unclamped Inductive Switching Circuit & Waveforms

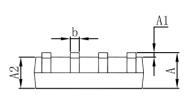


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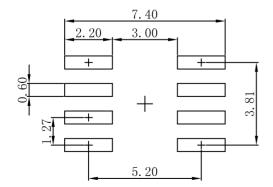
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1.270 (BSC)		0.050 (BSC)		
E	5.800	6.200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0 °	8°	0 °	8°	



Note: 1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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